

CMP PAD CONDITIONER

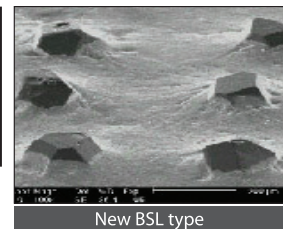


Advantages

- Strong diamond holding force : Chemical reaction + Mechanical contact
- Corrosion resistance : Carbide interface between diamond & bond material
- Longer lifetime : Utilization of edges by diamond face
- Maximized diamond chip pocket by high diamond exposure
→ Excellent conditioning efficiency and pad debris removal rate

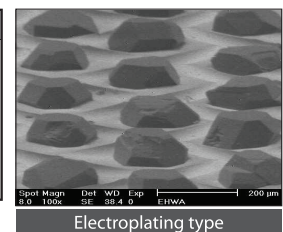
Applications

	Polished materials
New BSL type (Double metal layer)	· Oxide CMP : BPSG , TEOS , PSG · Metal CMP : Al , W , Cu
Electroplating type	· STI , PGI , Poly-si , TSV CMP → Cu , Poly-Si

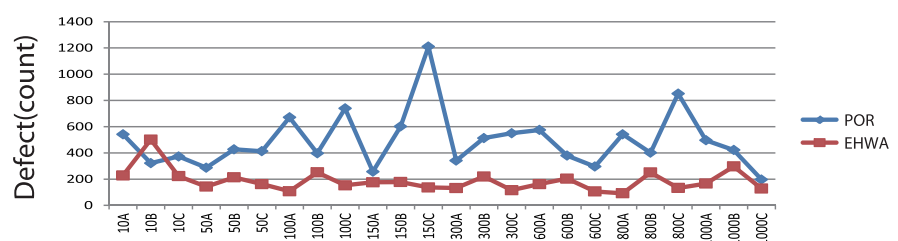


Available Product Spec.

Machines (model)	Pad cut rate
· AMAT (Mirra/Reflexion) · Ebara (F-Rex200/300 , EPO-222(H)) · Novellus (Auriga, CMP200/300, Avantgaard 776 (676) , Momentum) · Strasbaugh (6DS-SP , 6ED) · Lam (Teres) , etc.	10 ~ 300 um/hr



Performance Data



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